

Silicon Carbide (SiC) **Schottky Diode** - EliteSiC, 10 A, 1200 V, D1, TO-247-3L

FFSH10120ADN-F155

Description

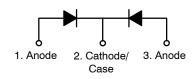
Silicon Carbide (SiC) Schottky Diodes use a completely new technology that provides superior switching performance and higher reliability compared to Silicon. No reverse recovery current, temperature independent switching characteristics, and excellent thermal performance sets Silicon Carbide as the next generation of power semiconductor. System benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size and cost.

Features

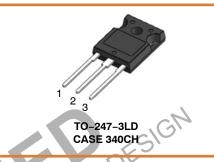
- Max Junction Temperature 175°C
- Avalanche Rated 55 mJ
- High Surge Current Capacity
- Positive Temperature Coefficient

- No Reverse Recovery/No Forward Recovery
 This Device is Pb–Free, Halogen Free/BFR Free and RoHS Compliant
 Applications
 General Purpose
 SMPS, Solar Inverter, UPS
 Power Switching Circuits

 A YWW
 ZZ
 FFSH10120



Schottky Diode



MARKING DIAGRAM



FFSH10120ADN

= Assembly Plant Code = Date Code (Year & Week) = Lot Traceability Code

= Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

ABSOLUTE MAXIMUM RATINGS (T_C = 25°C unless otherwise noted) (per leg)

Symbol	Parameter	Value	Unit	
V_{RRM}	Peak Repetitive Reverse Voltage	1200	V	
E _{AS}	Single Pulse Avalanche Energy (Note 1)	Single Pulse Avalanche Energy (Note 1)		
I _F	Continuous Rectified Forward Current @ T _C <	5* / 10**	Α	
	Continuous Rectified Forward Current @ T _C <	Continuous Rectified Forward Current @ T _C < 135°C		
I _{F, Max}	Non-Repetitive Peak Forward Surge Current	T _C = 25°C, 10 μs	380	Α
		T _C = 150°C, 10 μs	330	V mJ A
I _{F,SM}	Non-Repetitive Forward Surge Current	, b		Α
I _{F,RM}	Repetitive Forward Surge Current			Α
Ptot	Power Dissipation	T _C = 25°C	83	W
		T _C = 150°C	14	W
T _J , T _{STG}	Operating and Storage Temperature Range	Operating and Storage Temperature Range		√ °C
	TO-247 Mounting Torque, M3 Screw	60	Ncm	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

NOTE: * Per leg, ** Per Device

THERMAL CHARACTERISTICS

Symbol	Parameter	10	Value	Unit
$R_{ heta JC}$	Thermal Resistance, Junction to Case, Max	JOE ON	1.8*/ 0.91**	°C/W

NOTE: * Per leg, ** Per Device

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted) (per leg)

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
V _F	Forward Voltage	I _F = 5 A, T _C = 25°C	_	1.45	1.75	V
		I _F = 5 A, T _C = 125°C	_	1.7	2.0	
•	15	I _F = 5 A, T _C = 175°C	-	2.0	2.4	
I _R	Reverse Current	V _R = 1200 V, T _C = 25°C	ı	ı	200	μΑ
	MO BLL	V _R = 1200 V, T _C = 125°C	-	-	300	
	OF OR	V _R = 1200 V, T _C = 175°C	-	-	400	
Q _C	Total Capacitive Charge	V = 800 V	-	37	-	nC
C	Total Capacitance	V _R = 1 V, f = 100 kHz	-	337	-	pF
		$V_R = 400 \text{ V}, f = 100 \text{ kHz}$	_	33	_	
		$V_R = 800 \text{ V, f} = 100 \text{ kHz}$	_	26	_	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

ORDERING INFORMATION

I	Part Number	Top Marking	Package	Shipping
	FFSH10120ADN-F155	FFSH10120ADN	TO-247-3LD	30 Units / Tube

^{1.} E_{AS} of 55 mJ is based on starting $T_J = 25$ °C, L = 0.5 mH, $I_{AS} = 15$ A, V = 50 V.

TYPICAL CHARACTERISTICS

 $(T_J = 25^{\circ}C \text{ UNLESS OTHERWISE NOTED}) \text{ (PER LEG)}$

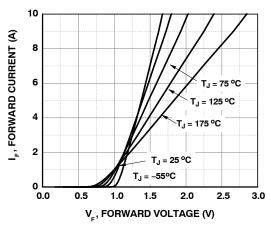


Figure 1. Forward Characteristics

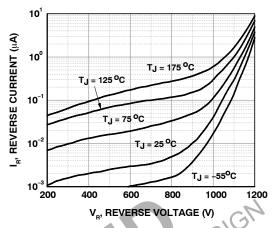


Figure 2. Reverse Characteristics

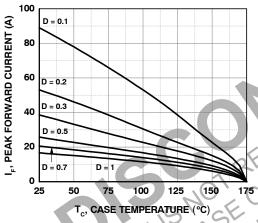


Figure 3. Current Derating

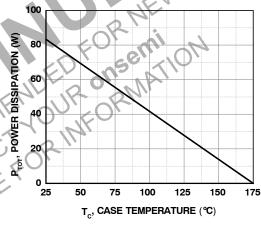


Figure 4. Power Derating

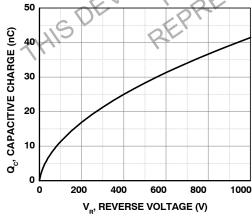


Figure 5. Capacitive Charge vs. Reverse Voltage

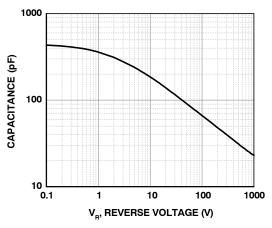


Figure 6. Capacitance vs. Reverse Voltage

TYPICAL CHARACTERISTICS

(T_J = 25°C UNLESS OTHERWISE NOTED)

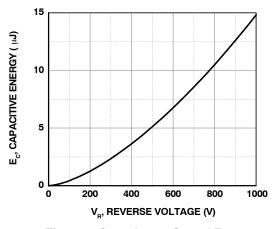
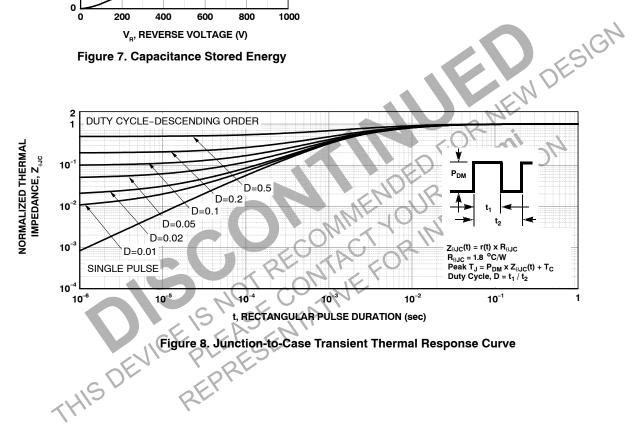
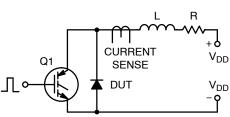


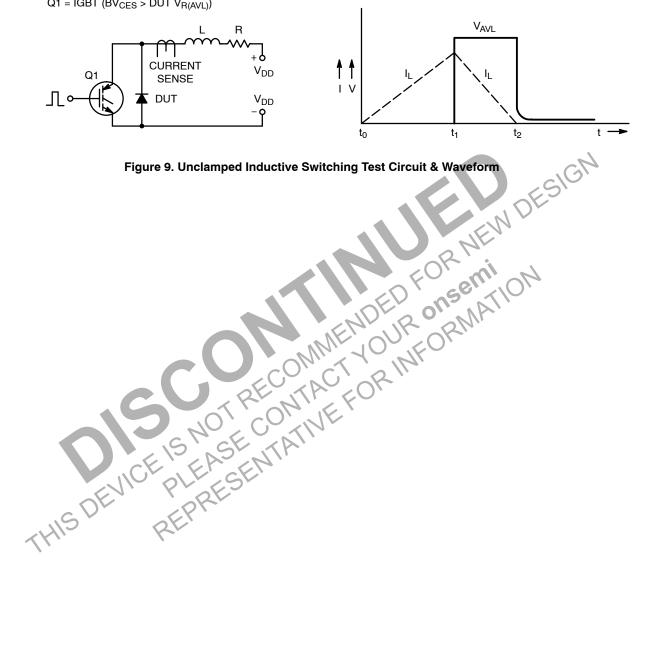
Figure 7. Capacitance Stored Energy



TEST CIRCUIT AND WAVEFORMS

L = 0.5 mH $R < 0.1 \Omega$ $V_{DD} = 50 \text{ V}$ EAVL = 1/2LI2 [V_{R(AVL)} / (V_{R(AVL)} - V_{DD})] Q1 = IGBT (BV_{CES} > DUT V_{R(AVL)})

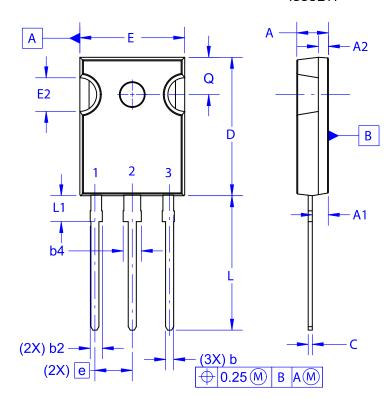




DATE 09 OCT 2019



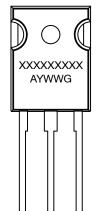
TO-247-3LD CASE 340CH **ISSUE A**





- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
 D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

GENERIC **MARKING DIAGRAM***



XXXX = Specific Device Code

= Assembly Location

WW

= Work Week

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

Ø P —			Ø <u>P1</u> D2
S E1 —	2)	D1

DIM	MILLIMETERS				
DIM	MIN	NOM	MAX		
Α	4.58	4.70	4.82		
A 1	2.29	2.475	2.66		
A2	1.40	1.50	1.60		
D	20.32	20.57	20.82		
Е	15.37	15.62	15.87		
E2	4.96	5.08	5.20		
е	~	5.56	~		
L	19.75	20.00	20.25		
L1	3.69	3.81	3.93		
ØΡ	3.51	3.58	3.65		
Q	5.34	5.46	5.58		
S	5.34	5.46	5.58		
b	1.17	1.26	1.35		
b2	1.53	1.65	1.77		
b4	2.42	2.54	2.66		
С	0.51	0.61	0.71		
D1	13.08	~	2		
D2	0.51	0.93	1.35		
E1	12.81	~	~		
Ø P 1	6.61	6.73	6.85		

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DESCRIPTION:	TO-247-3LD		PAGE 1 OF 1	

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